OCTOBER 1976 – REVISED MARCH 1988

- **Synchronous Load**
- **Direct Overriding Clear**
- **Parallel to Serial Conversion**

TYPE	TYPICAL MAXIMUM CLOCK FREQUENCY	TYPICAL POWER DISSIPATION
'166	35 MHz	360 mW
'LS166A	35 MHz	100 mW

description

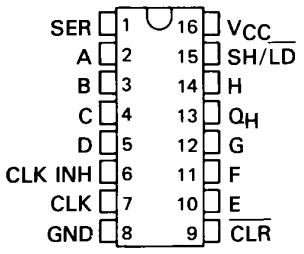
The '166 and 'LS166A 8-bit shift registers are compatible with most other TTL logic families. All '166 and 'LS166A inputs are buffered to lower the drive requirements to one Series 54/74 or Series 54LS/74LS standard load, respectively. Input clamping diodes minimize switching transients and simplify system design.

These parallel-in or serial-in, serial-out shift registers have a complexity of 77 equivalent gates on a monolithic chip. They feature gated clock inputs and an overriding clear input. The parallel-in or serial-in modes are established by the shift/load input. When high, this input enables the serial data input and couples the eight flip-flops for serial shifting with each clock pulse. When low, the parallel (broadside) data inputs are enabled and synchronous loading occurs on the next clock pulse. During parallel loading, serial data flow is inhibited. Clocking is accomplished on the low-to-high-level edge of the clock pulse through a two-input positive NOR gate permitting one input to be used as a clock-enable or clock-inhibit function. Holding either of the clock inputs high inhibits clocking; holding either low enables the other clock input. This, of course, allows the system clock to be free-running and the register can be stopped on command with the other clock input. The clock inhibit input should be changed to the high level only while the clock input is high. A buffered, direct clear input overrides all other inputs, including the clock, and sets all flip-flops to zero.

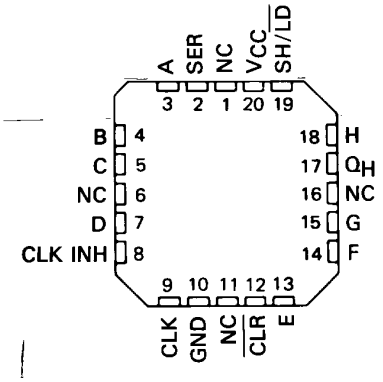
FUNCTION TABLE

INPUTS						INTERNAL OUTPUTS		OUTPUT
CLEAR	SHIFT/LOAD	CLOCK INHIBIT	CLOCK	SERIAL	PARALLEL A...H	Q_A	Q_B	Q_H
L	X	X	X	X	X	L	L	L
H	X	L	L	X	X	Q_{A0}	Q_{B0}	Q_{H0}
H	L	L	↑	X	a...h	a	b	h
H	H	L	↑	H	X	H	Q_{An}	Q_{Gn}
H	H	L	↑	L	X	L	Q_{An}	Q_{Gn}
H	X	H	↑	X	X	Q_{A0}	Q_{B0}	Q_{H0}

SN54166, SN54LS166A . . . J OR W PACKAGE
SN74166 . . . N PACKAGE
SN74LS166A . . . D OR N PACKAGE
(TOP VIEW)

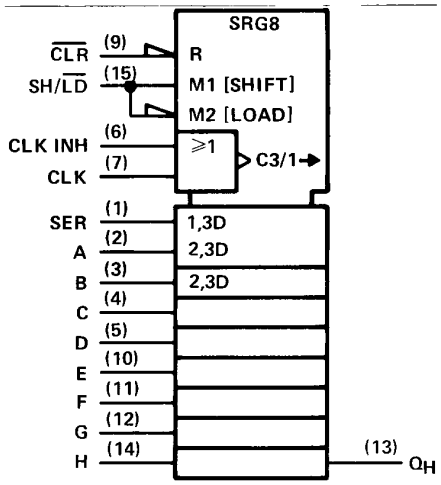


SN54LS166A . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

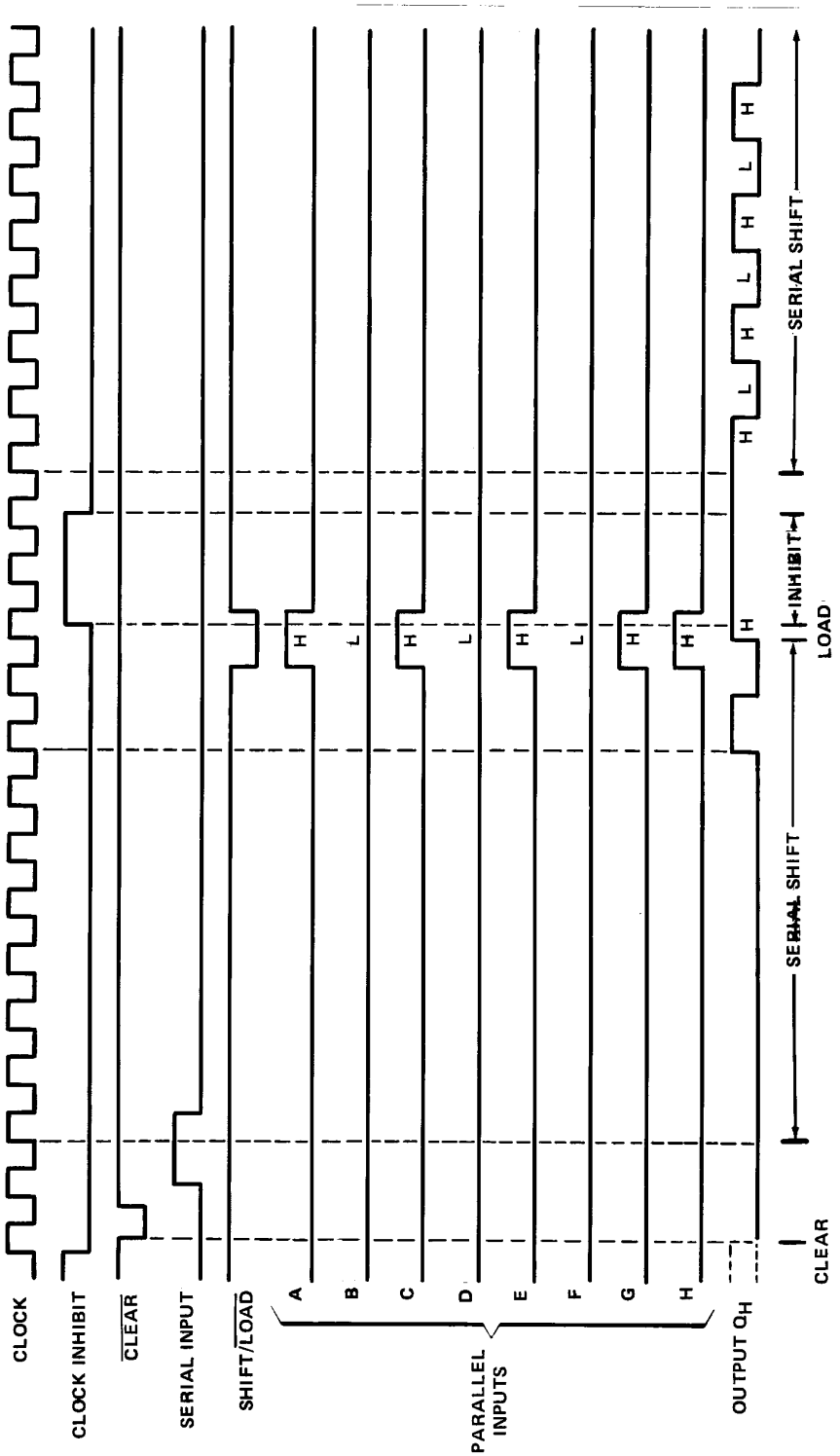
logic symbol†



†This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for D, J, N, and W packages.

PRODUCTION DATA documents contain information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

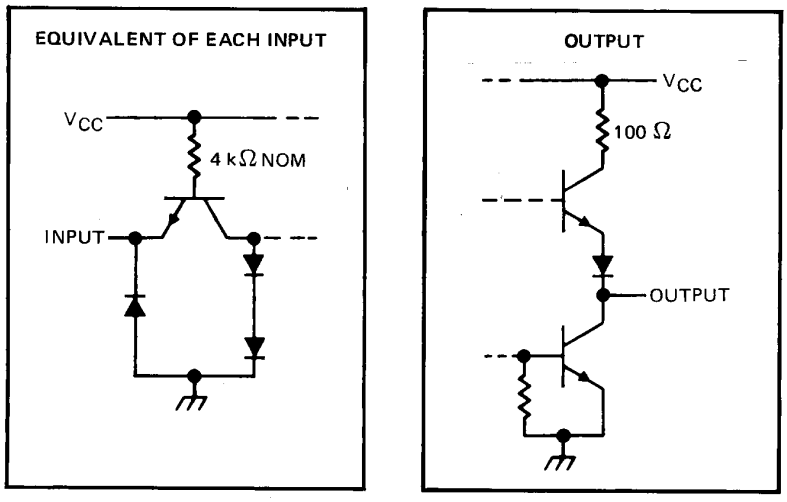
typical clear, shift, load, inhibit, and shift sequences



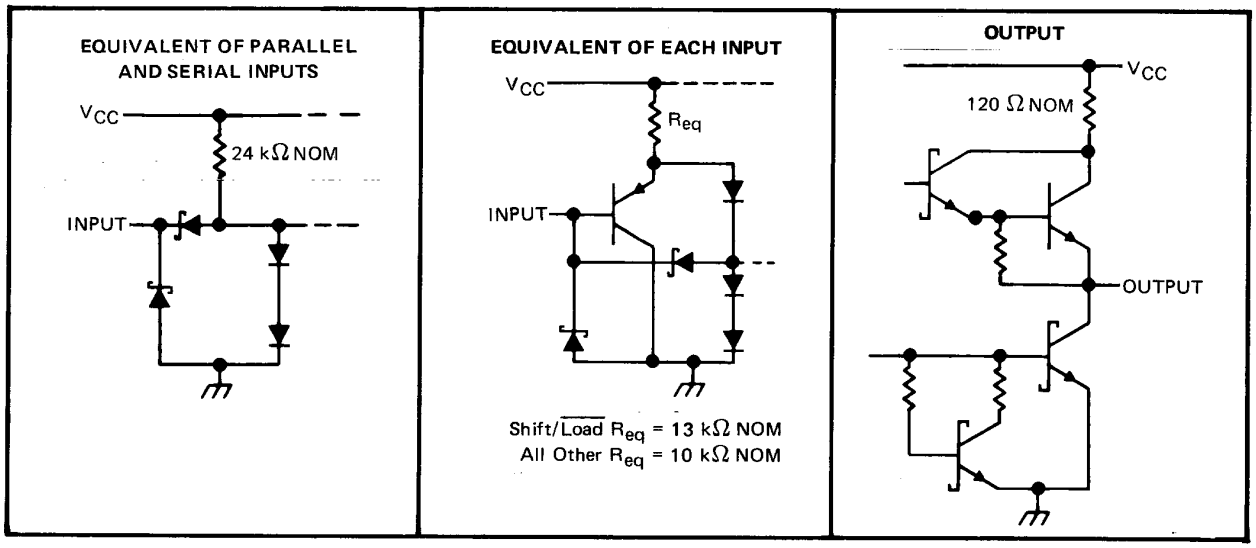
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schematics of inputs and outputs

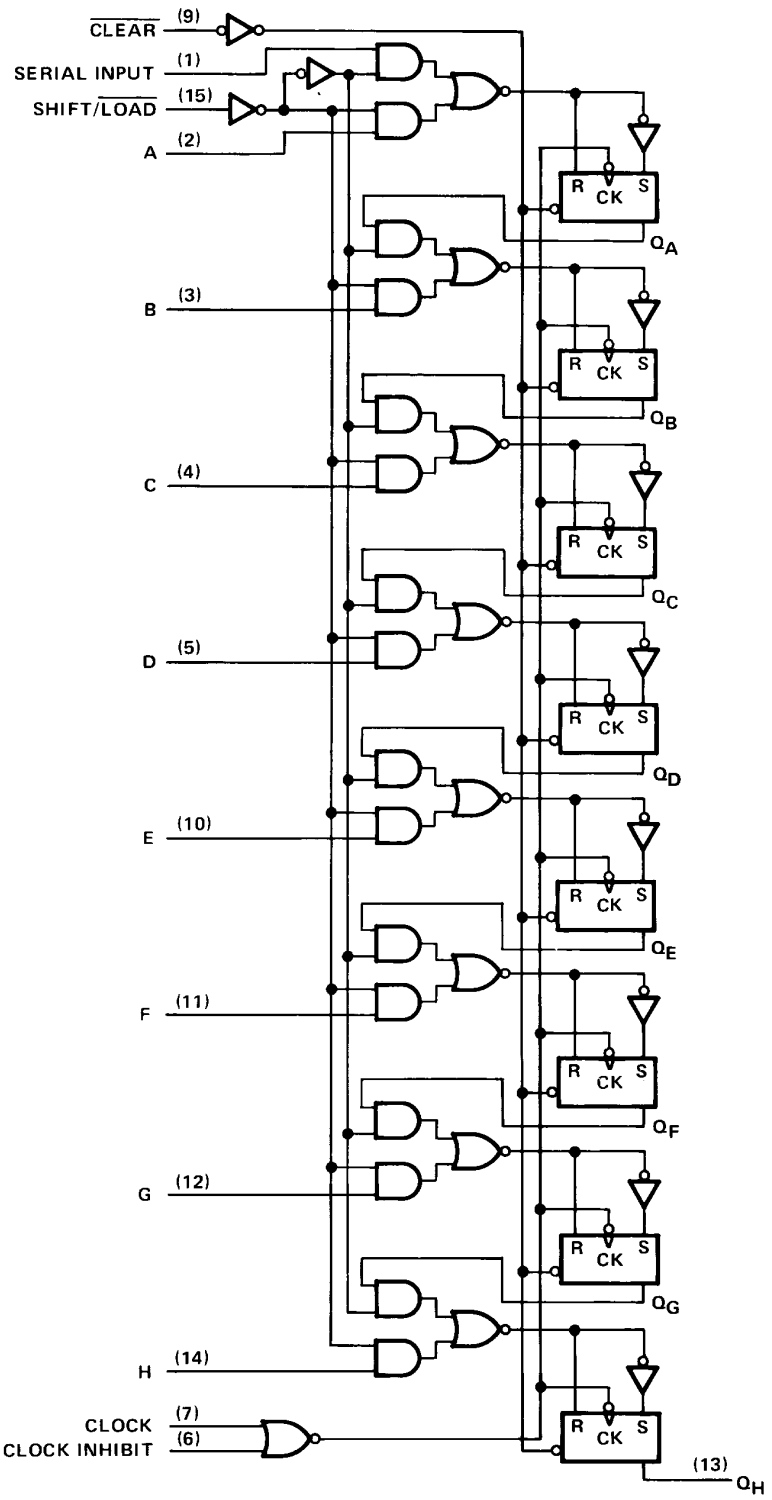
'166



'LS166A



logic diagram (positive logic)



Pin numbers shown are for D, J, N, and W packages.

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage . . . . . 5.5 V
Operating free-air temperature range: SN54166 (see Note 2) . . . . . −55°C to 125°C
SN74166 . . . . . 0°C to 70°C
Storage temperature range . . . . . −65°C to 150°C

recommended operating conditions

	SN54166			SN74166			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}	4.5	5	5.5	4.75	5	5.25	V
High-level output current, I_{OH}			−800			−800	μA
Low-level output current, I_{OL}			16			16	mA
Clock frequency, f_{clock}	0		25	0		25	MHz
Width of clock or clear pulse, t_w (see Figure 1)	20			20			ns
Mode-control setup time, t_{su}	30			30			ns
Data setup time, t_{su} (see Figure 1)	20			20			ns
Hold time at any input, t_h (see Figure 1)	0			0			ns
Operating free-air temperature, T_A (see Note 2)	−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†	SN54166			SN74166			UNIT
			MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IH}	High-level input voltage		2			2			V
V_{IL}	Low-level input voltage				0.8			0.8	V
V_{IK}	Input clamp voltage	V_{CC} = MIN, I_I = −12 mA			−1.5			−1.5	V
V_{OH}	High-level output voltage	V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = 0.8 V, I_{OH} = −800 μA	2.4	3.4		2.4	3.4		V
V_{OL}	Low-level output voltage	V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = 0.8 V, I_{OL} = 16 mA		0.2	0.4		0.2	0.4	V
I_I	Input current at maximum input voltage	V_{CC} = MAX, V_I = 5.5 V			1			1	mA
I_{IH}	High-level input current	V_{CC} = MAX, V_I = 2.4 V			40			40	μA
I_{IL}	Low-level input current	V_{CC} = MAX, V_I = 0.4 V			−1.6			−1.6	mA
I_{OS}	Short-circuit output current§	V_{CC} = MAX	−20		−57	−18		−57	mA
I_{CC}	Supply current	V_{CC} = MAX, See Note 3		90	127		90	127	mA

†For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡All typical values are at V_{CC} = 5 V, T_A = 25°C.
§Not more than one output should be shorted at a time.

NOTES: 1. Voltage values are with respect to network ground terminal.
2. An SN54166 in the W package operating at free-air temperatures above 113°C requires a heat-sink that provides a thermal resistance from case to free air, $R_{\theta CA}$, of not more than 48°C/W.
3. With all outputs open, 4.5 V applied to the serial input, all other inputs except the clock grounded, I_{CC} is measured after a momentary ground, then 4.5 V, is applied to the clock.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
f_{max}	Maximum clock frequency	C_L = 15 pF, R_L = 400 Ω, See Figure 1	25	35		MHz
t_{PHL}	Propagation delay time, high-to-low-level output from clear			23	35	ns
t_{PHL}	Propagation delay time, high-to-low-level output from clock			20	30	ns
t_{PLH}	Propagation delay time, low-to-high-level output from clock			17	26	ns

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage . . . . . 7 V
Operating free-air temperature range: SN54LS166A . . . . . −55°C to 125°C
SN74LS166A . . . . . 0°C to 70°C
Storage temperature range . . . . . −65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		SN54LS166A			SN74LS166A			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.7			0.8	V
I_{OH}	High-level output current			−0.4			−0.4	mA
I_{OL}	Low-level output current			4			8	mA
f_{clock}	Clock frequency	0		25	0		25	MHz
t_w	Width of clear pulse (See Figure 1)	20			20			ns
t_w	Width of clock pulse (See Figure 1)	25			25			
t_{su}	Mode-control setup time	30			30			ns
t_{su}	Data setup time (See Figure 1)	20			20			ns
t_h	Hold time at any input (See Figure 1 and Note 4)	0			0			ns
T_A	Operating free air temperature	−55		125	0		70	°C

NOTE 4: The hold time limit of 0 ns applies only if the rise time is less than or equal to 10 ns.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†		SN54LS166A			SN74LS166A			UNIT
			MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}	V_{CC} = MIN, I_I = −18 mA				−1.5			−1.5	V
V_{OH}	V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = MAX, I_{OH} = −0.4 mA		2.5	3.4		2.7	3.4		V
V_{OL}	V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = MAX	I_{OL} = 4 mA		0.25	0.4		0.25	0.4	V
		I_{OL} = 8 mA					0.35	0.5	
I_I	V_{CC} = MAX, V_I = 7 V				0.1			0.1	mA
I_{IH}	V_{CC} = MAX, V_I = 2.7 V				20			20	μA
I_{IL}	V_{CC} = MAX, V_I = 0.4 V				−0.4			−0.4	mA
I_{OS}§	V_{CC} = MAX		−20		−100	−20		−100	mA
I_{CC}	V_{CC} = MAX, See Note 5			20	32		20	32	mA

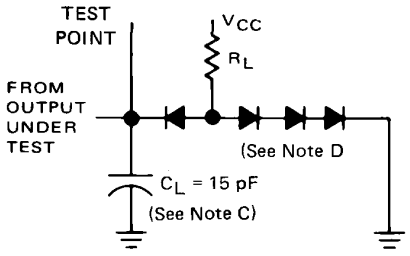
†For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡All typical values are at V_{CC} = 5 V, T_A = 25°C.
§Not more than one output should be shorted at a time, and duration for short-circuit should not exceed one second.
NOTE 5: With all outputs open, 4.5 V applied to the serial input and all other inputs except the clock grounded, I_{CC} is measured after a momentary ground, than 4.5 V, is applied to clock.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
f_{max}	Maximum clock frequency	C_L = 15 pF, R_L = 2 kΩ, See Figure 1	25	35		MHz
t_{PHL}	Propagation delay time, high-to-low-level output from clear			19	30	ns
t_{PHL}	Propagation delay time, high-to-low-level output from clock		7	14	25	ns
t_{PLH}	Propagation delay time, low-to-high-level output from clock		5	11	20	ns

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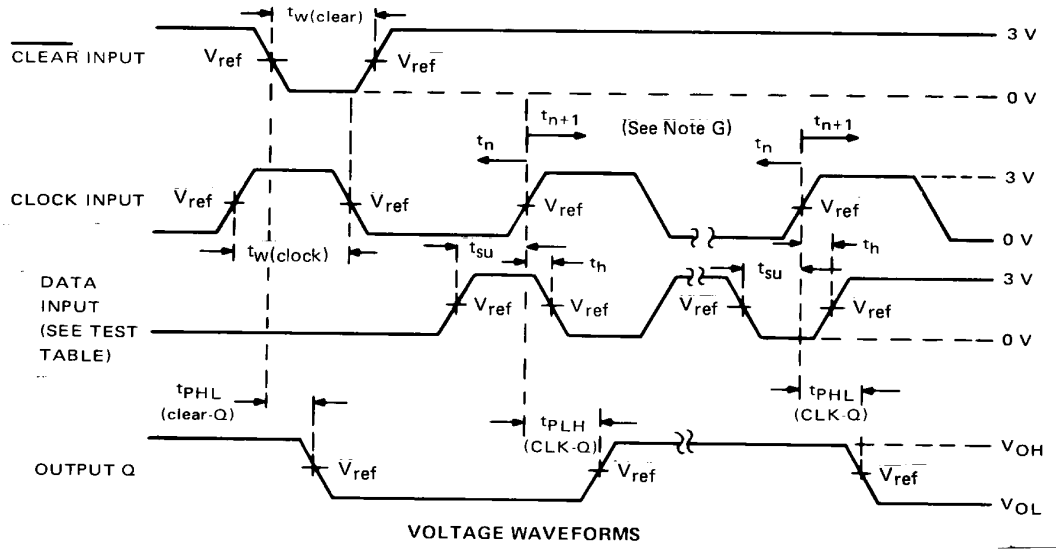
PARAMETER MEASUREMENT INFORMATION



LOAD FOR OUTPUT UNDER TEST

TEST TABLE FOR SYNCHRONOUS INPUTS

DATA INPUT FOR TEST	SHIFT/$\overline{\text{LOAD}}$	OUTPUT TESTED (SEE NOTE F)
H	0 V	Q_H at t_{n+1}
Serial Input	4.5 V	Q_H at t_{n+8}



VOLTAGE WAVEFORMS

NOTE: A. All pulse generators have the following characteristics: $Z_{out} \approx 50\Omega$; for '166, $t_r \leq 7$ ns and $t_f \leq 7$ ns; for 'LS166A, $t_r \leq 15$ ns and $t_f \leq 6$ ns.

B. The clock pulse has the following characteristics: $t_{w(clock)} \leq 20$ ns and PRR = 1 MHz. The clear pulse has the following characteristics: $t_{w(clear)} \leq 20$ ns and $t_{hold} = 0$ ns. When testing f_{max}, vary the clock PRR.

C. C_L includes probe and jig capacitance.

D. All diodes are 1N3064, 1N916, or equivalent.

E. A clear pulse is applied prior to each test.

F. Propagation delay times (t_{PLH} and t_{PHL}) are measured at t_{n+1}. Proper shifting of data is verified at t_{n+8} with a functional test.

G. t_n = bit time before clocking transition
t_{n+1} = bit time after one clocking transition
t_{n+8} = bit time after eight clocking transitions

H. For '166 V_{ref} = 1.5 V; for 'LS166A V_{ref} = 1.3 V.

FIGURE 1

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9558301QEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9558301QE A SNJ54166J	Samples
5962-9558301QFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9558301QF A SNJ54166W	Samples
5962-9558301QFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9558301QF A SNJ54166W	Samples
8001701EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	8001701EA SNJ54LS166AJ	Samples
8001701EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	8001701EA SNJ54LS166AJ	Samples
8001701FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	8001701FA SNJ54LS166AW	Samples
8001701FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	8001701FA SNJ54LS166AW	Samples
JM38510/30609B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30609B2A	Samples
JM38510/30609B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30609B2A	Samples
JM38510/30609BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30609BEA	Samples
JM38510/30609BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30609BEA	Samples
M38510/30609B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30609B2A	Samples
M38510/30609B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30609B2A	Samples
M38510/30609BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30609BEA	Samples
M38510/30609BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30609BEA	Samples
SN54166J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54166J	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN54166J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54166J	Samples
SN54LS166AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS166AJ	Samples
SN54LS166AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS166AJ	Samples
SN74166N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74166N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74166N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74166N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74LS166AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS166A	Samples
SN74LS166AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS166A	Samples
SN74LS166ADG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS166A	Samples
SN74LS166ADG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS166A	Samples
SN74LS166ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS166A	Samples
SN74LS166ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS166A	Samples
SN74LS166AJ	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	0 to 70		
SN74LS166AJ	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	0 to 70		
SN74LS166AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS166AN	Samples
SN74LS166AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS166AN	Samples
SN74LS166AN3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74LS166AN3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74LS166ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS166A	Samples
SN74LS166ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS166A	Samples
SNJ54166J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9558301QEA	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
										SNJ54166J	
SNJ54166J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9558301QE A SNJ54166J	Samples
SNJ54166W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9558301QF A SNJ54166W	Samples
SNJ54166W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9558301QF A SNJ54166W	Samples
SNJ54LS166AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS 166AFK	Samples
SNJ54LS166AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS 166AFK	Samples
SNJ54LS166AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	8001701EA SNJ54LS166AJ	Samples
SNJ54LS166AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	8001701EA SNJ54LS166AJ	Samples
SNJ54LS166AW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	8001701FA SNJ54LS166AW	Samples
SNJ54LS166AW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	8001701FA SNJ54LS166AW	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54166, SN54LS166A, SN74166, SN74LS166A :

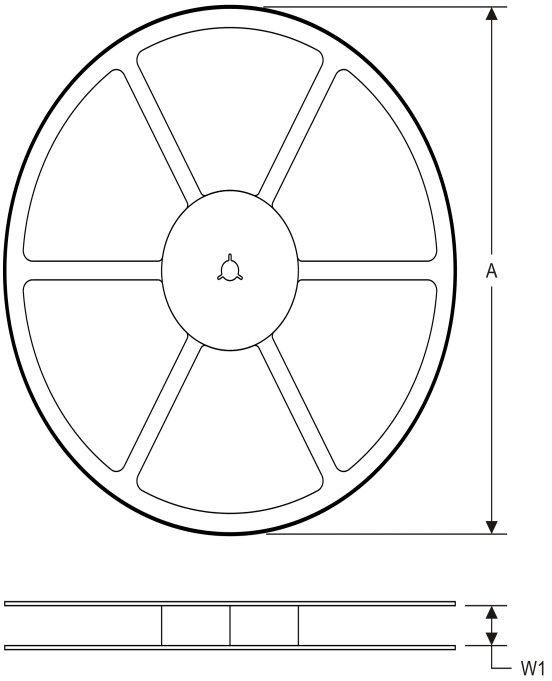
- Catalog: SN74166, SN74LS166A
- Military: SN54166, SN54LS166A

NOTE: Qualified Version Definitions:

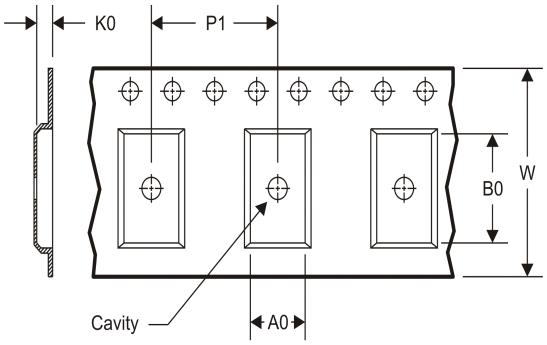
- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



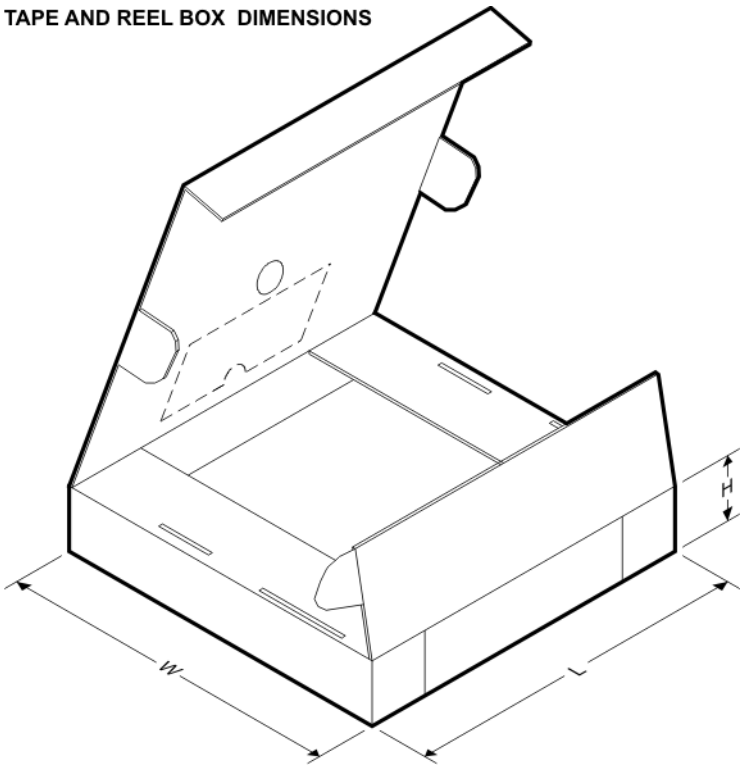
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS166ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS166ANSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



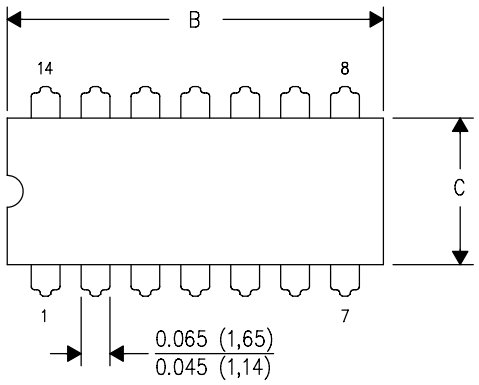
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS166ADR	SOIC	D	16	2500	333.2	345.9	28.6
SN74LS166ANSR	SO	NS	16	2000	367.0	367.0	38.0

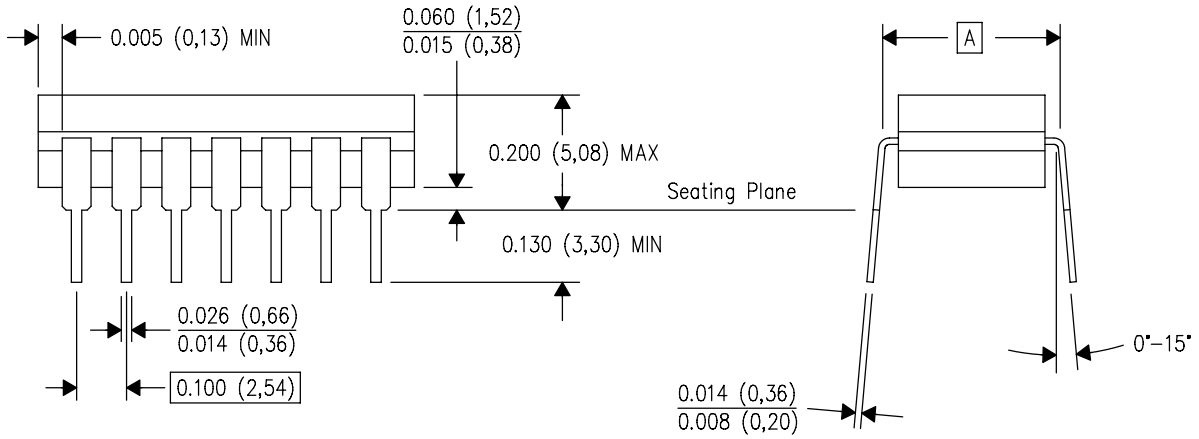
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



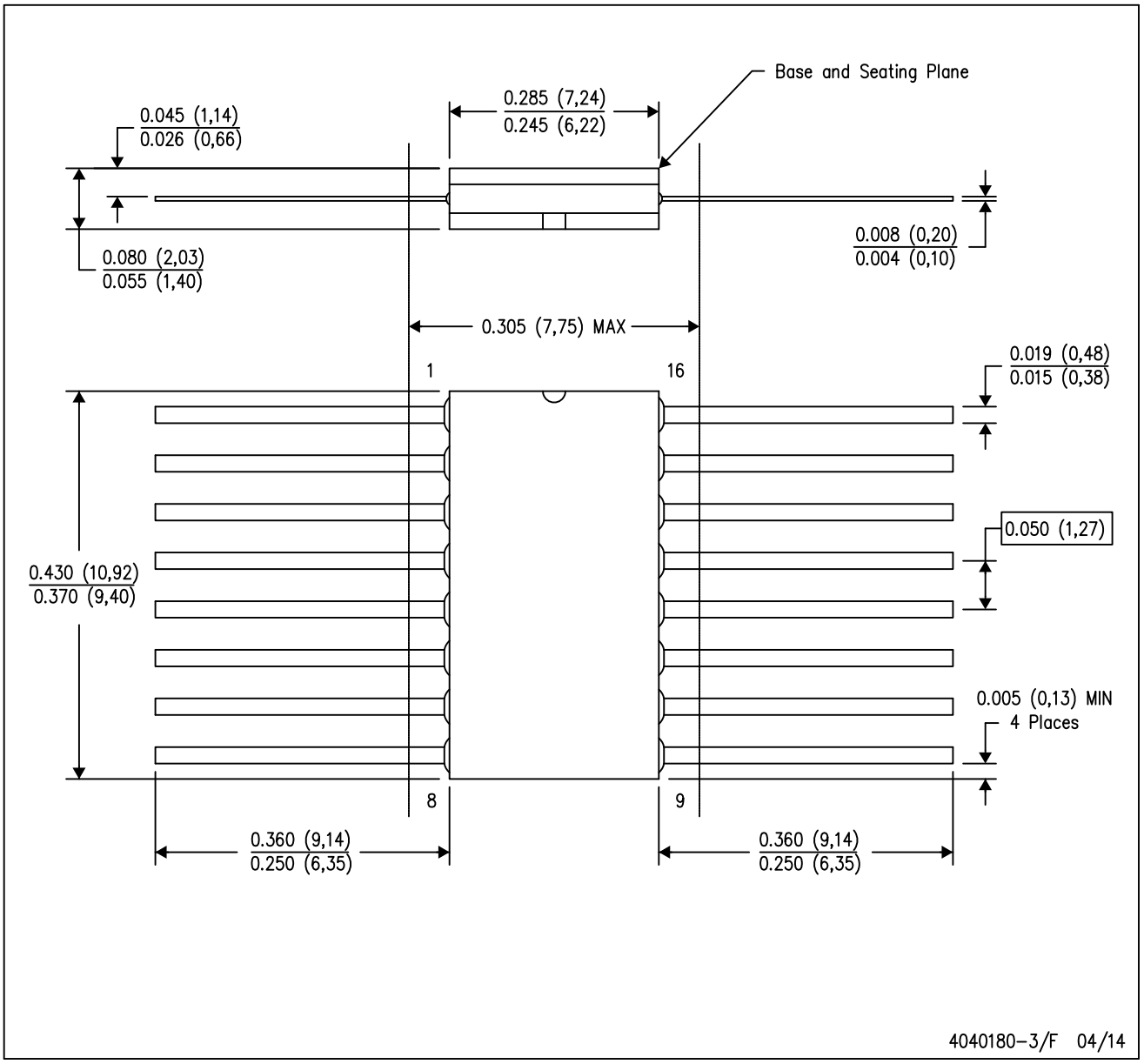
DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

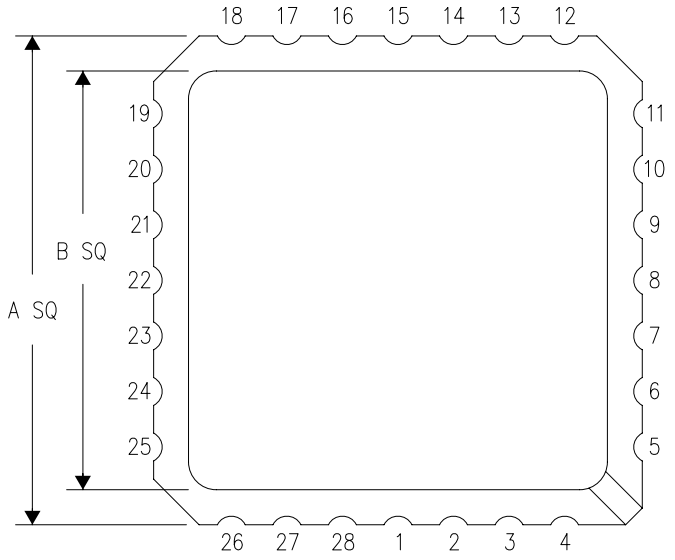
W (R–GDFP–F16) CERAMIC DUAL FLATPACK



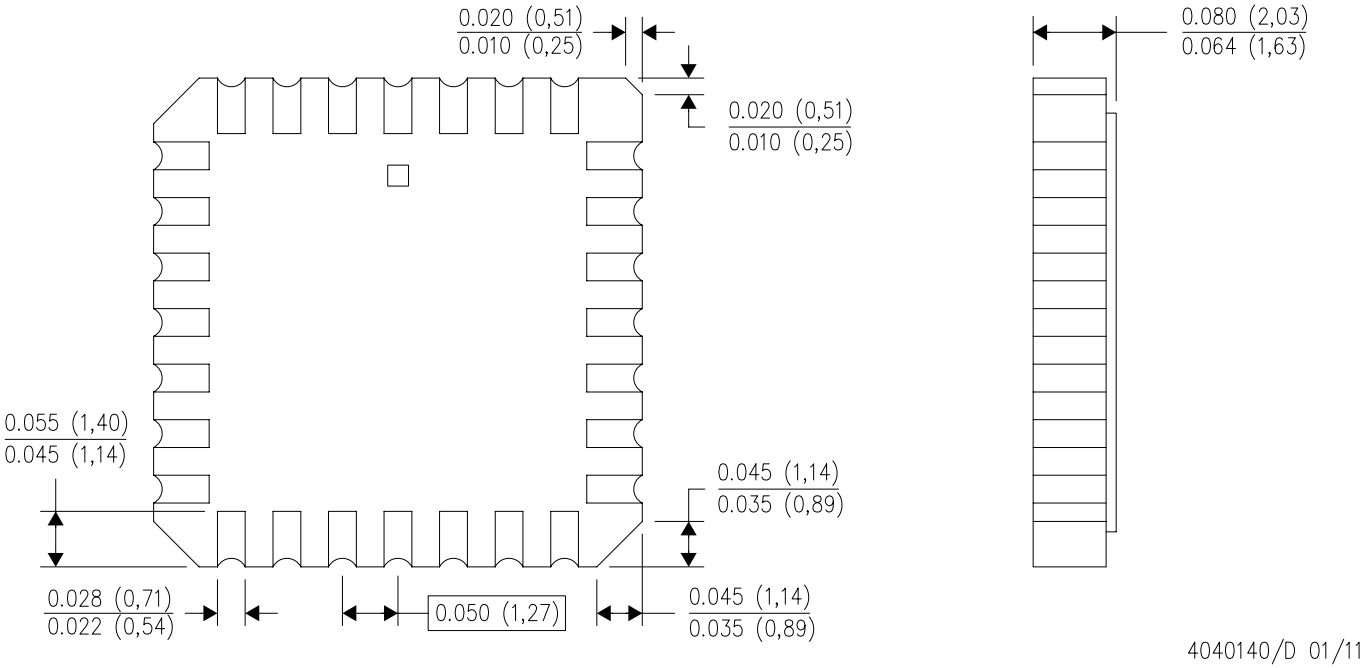
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL STD 1835 GDFP2–F16

FK (S–CQCC–N**) LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



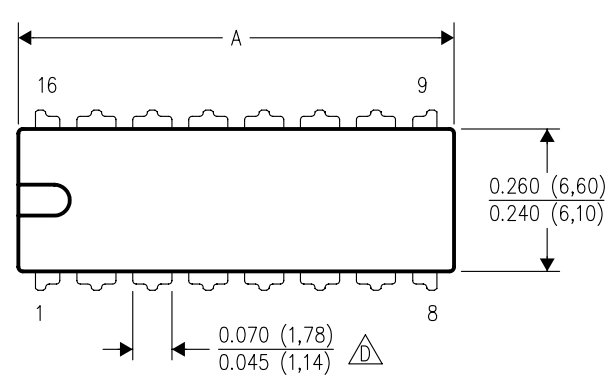
4040140/D 01/11

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a metal lid.
D. Falls within JEDEC MS–004

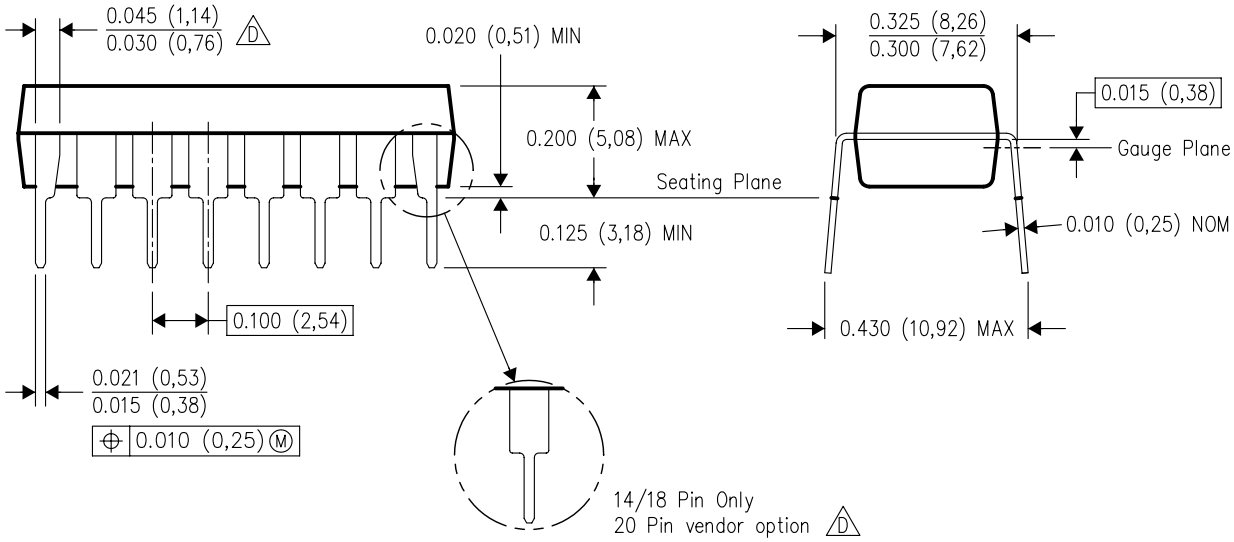
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



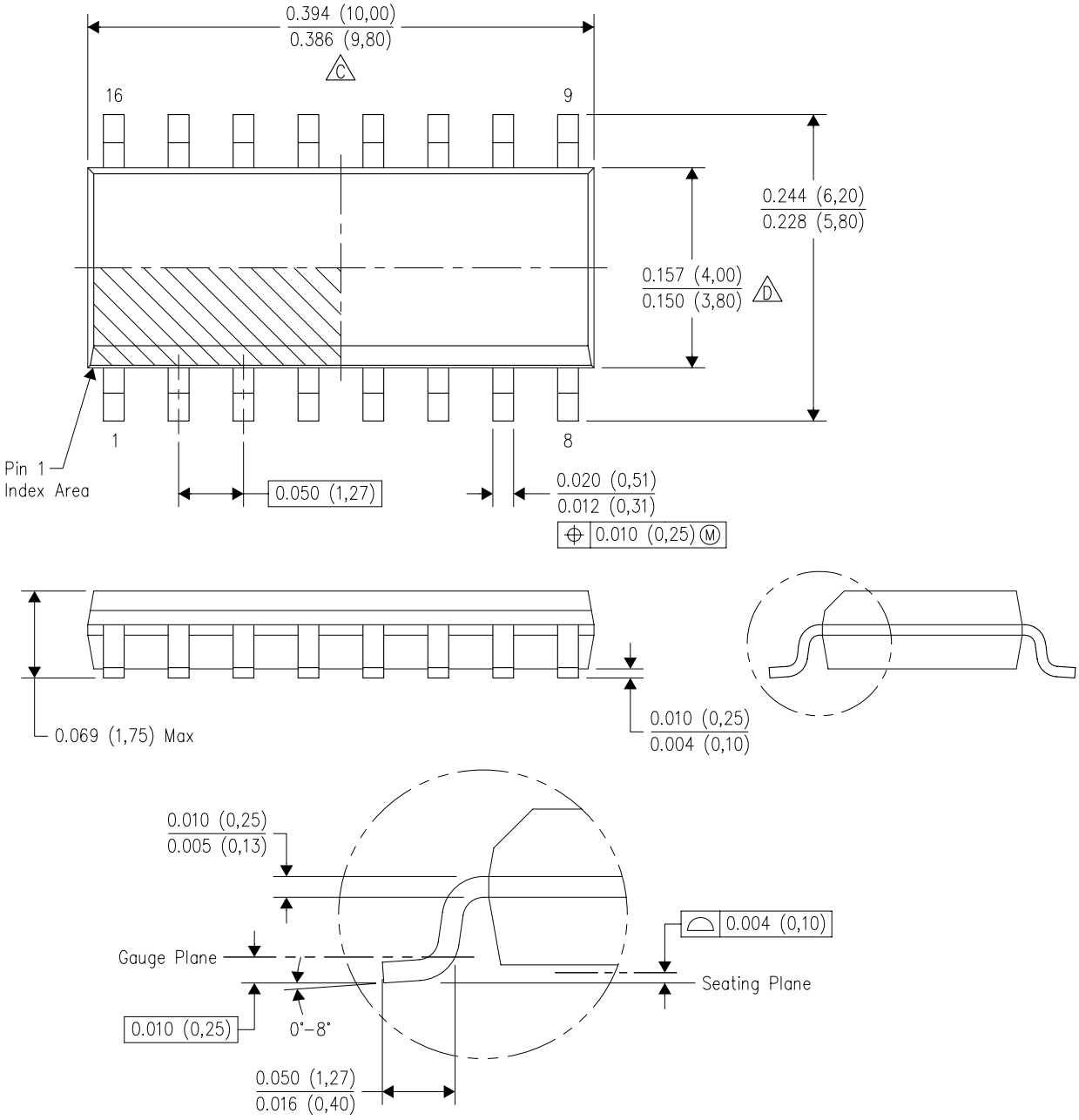
DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

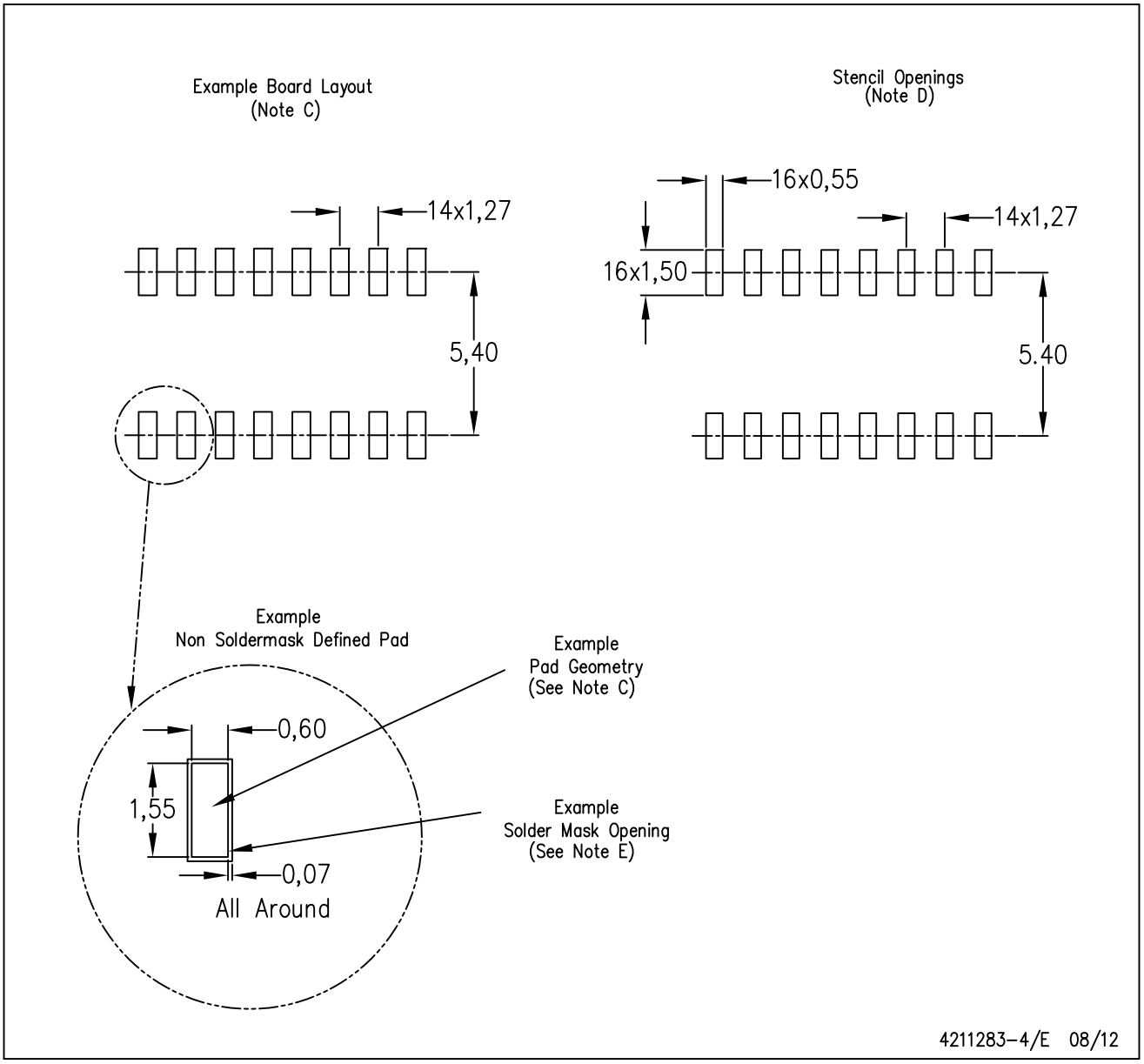
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R–PDSO–G16) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AC.

D (R–PDSO–G16) PLASTIC SMALL OUTLINE

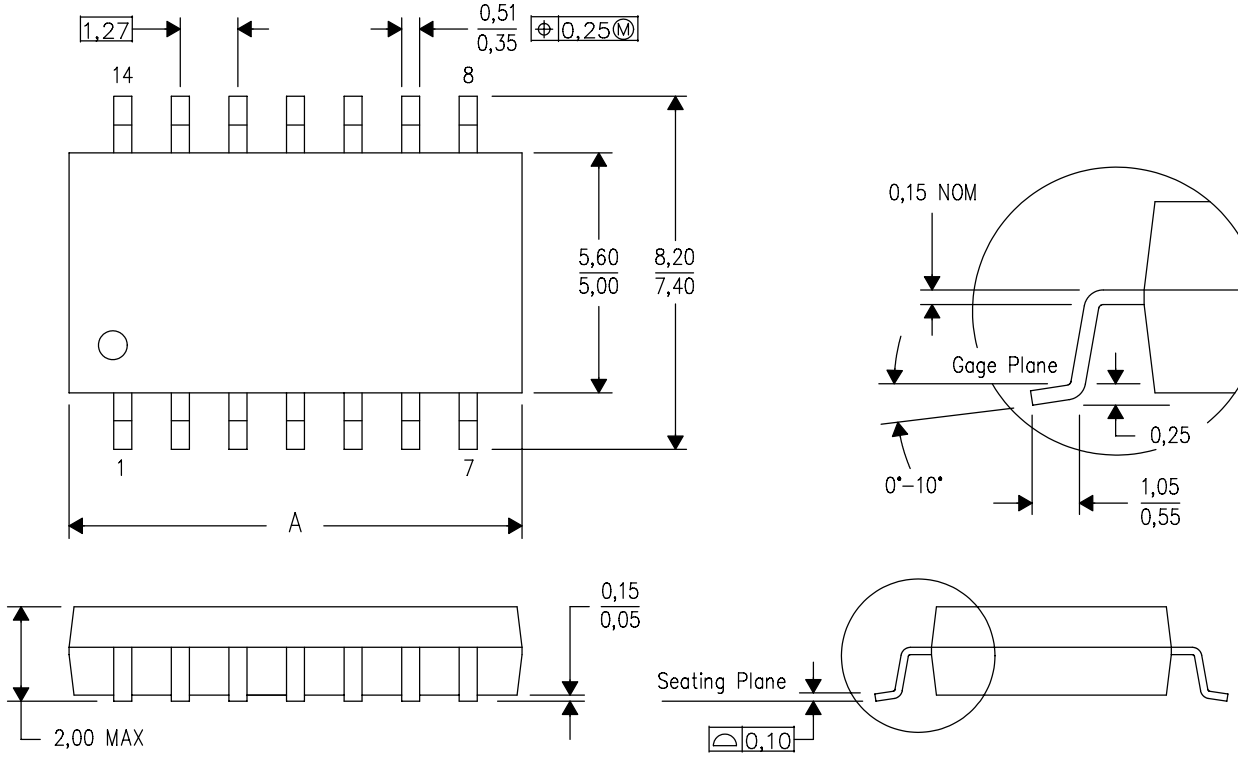


NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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